

ABSTRACT OF THE DISCLOSURE

A leadframe to be used in a semiconductor device comprises a plurality of parallel first leads and a plurality of parallel second leads. The pitch of the first leads is different from that of the second leads, and the first leads are joined end-to-end with the second leads. To obtain a leadframe for DIP packages, the first leads are encapsulated in a package and the second leads are allowed to project from the package. To obtain a leadframe for SOP packages, the first leads and the second leads are allowed to project from a package and the second leads are cut off later.